



VMDSEMI

VFPB012R140NA

Datasheet



VMDSEMI

General Description

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
120V	14mΩ@10V	60A
	16mΩ@4.5V	

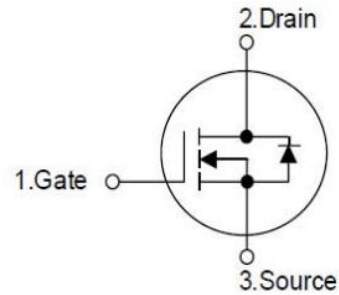
Symbol


Figure 1 Symbol of VFPB012R140NA

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Fast switching and soft recovery
- Excellent reliability and uniform

Application

- Switched mode power supply
- Solar inverter
- UPS and energy inverter
- PD charger
- Motor driver

Package Type


Figure 2 Package Type of VFPB012R140NA

VMDSEMI

Ordering Information

Product Name	Package
VFPB012R140NA	PDFN5*6

Absolute Maximum Ratings ($T_J=25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	120	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^{Note 1} , $T_C=25^\circ\text{C}$	I_D	60	A
Pulsed Drain Current ^{Note 2}	I_{DM}	180	A
Max Power Dissipation ^{Note 3} , $T_C=25^\circ\text{C}$	P_D	100	W
Avalanche Current, Single Pulse ^{Note 5}	I_{AS}	15	A
Avalanche Energy, Single Pulse ^{Note 5}	E_{AS}	71	mJ
Operation Junction temperature	T_J	-55 to 150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		1.25		$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient ^{Note 4}	$R_{\theta JA}$		62		

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_D is based on max junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^\circ\text{C}$.
- 5) $V_{DS}=25\text{ V}, V_{GS}=10\text{ V}, L=0.5\text{ mH}$, starting $T_J=25\text{ }^\circ\text{C}$.

Electrical Characteristics($T_J=25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=120V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	2	2.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$		7.7	14	$m\Omega$
		$V_{GS}=4.5V, I_D=10A$		9.1	16	$m\Omega$
Gate Resistance	R_G	$V_{GS}=0V, V_{DS}=0V, f=1MHz$		4.2		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{GS}=0V$		2245		pF
Output Capacitance	C_{OSS}	$V_{DS}=25V$		1223		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		44		pF
Turn-on Delay Time	$t_{d(on)}$	$V_{GS}=10V,$		6.4		ns
Rise Time	t_r	$V_{DS}=60V,$		42.9		
Turn-off Delay Time	$t_{d(off)}$	$I_D=20A$		64.4		
Fall Time	t_f	$R_G=6.8\Omega$		65.1		
Switching Characteristics						
Total Gate Charge (@ $V_{GS}=10V$)	Q_g	$V_{GS}=0\text{ to }10V$ $V_{DS}=60V$ $I_D=30A$		38.1		nC
Total Gate Charge (@ $V_{GS}=4.5V$)	Q_g			16.4		
Gate to Source Charge	Q_{gs}			8.1		
Gate to Drain Charge	Q_{gd}			5.8		
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=20A$		0.8	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=50V$		53.4		ns
Reverse Recovery Charge	Q_{rr}	$I_F=10A$		170.8		nC
Peak Reverse Recovery Current	I_{rrm}	$di/dt=100A/\mu s$		6.4		A

Typical Performance Characteristics

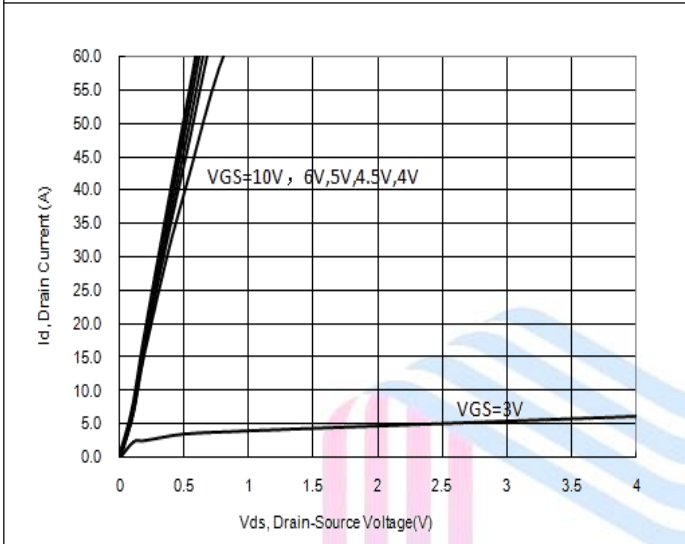
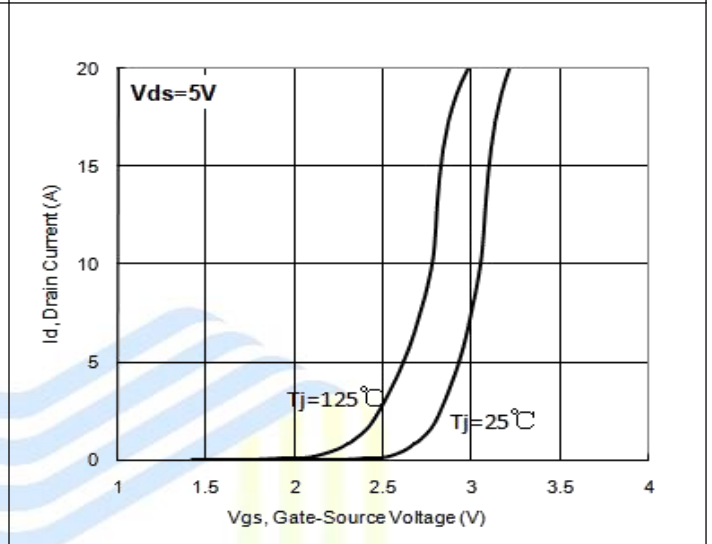
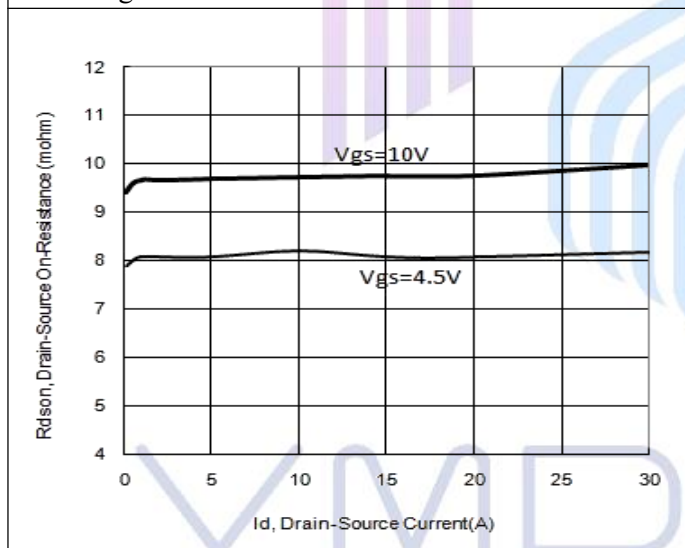
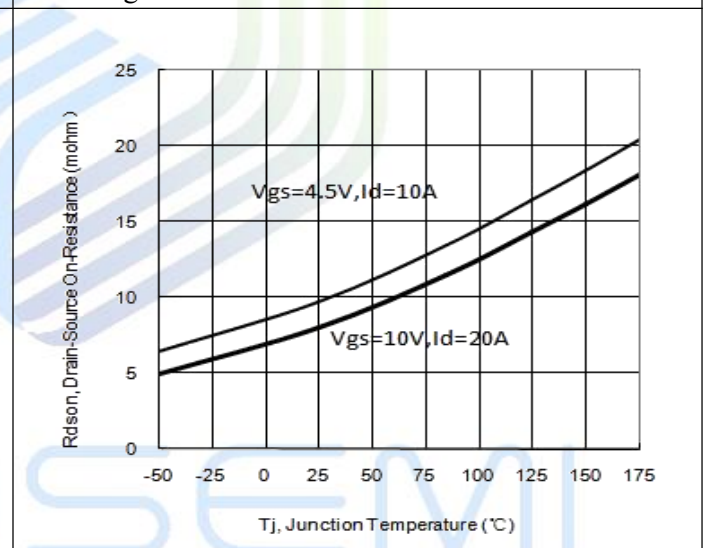
Figure 3: Typ. Output Characteristics

Figure 4: Typ. Transfer Characteristics

Figure 5: Drain-Source On-State Resistance

Figure 6: Drain-Source On-State Resistance


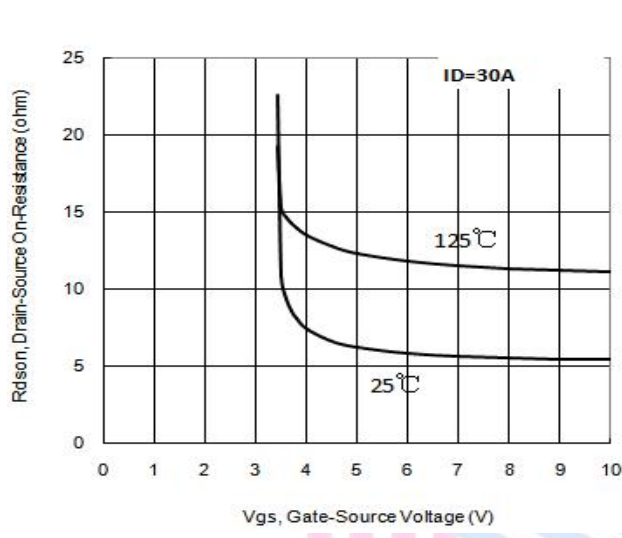
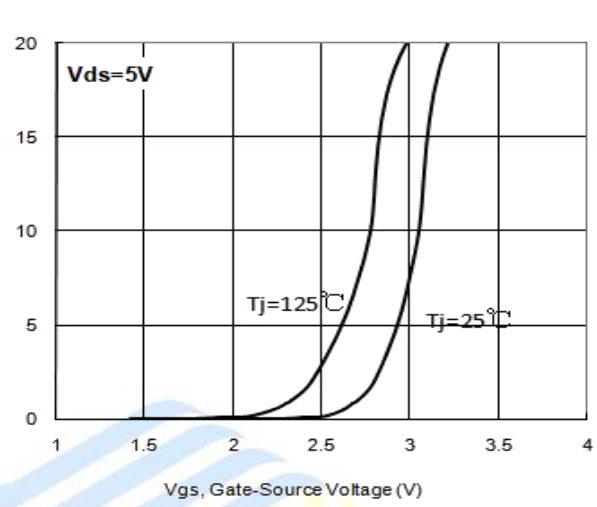
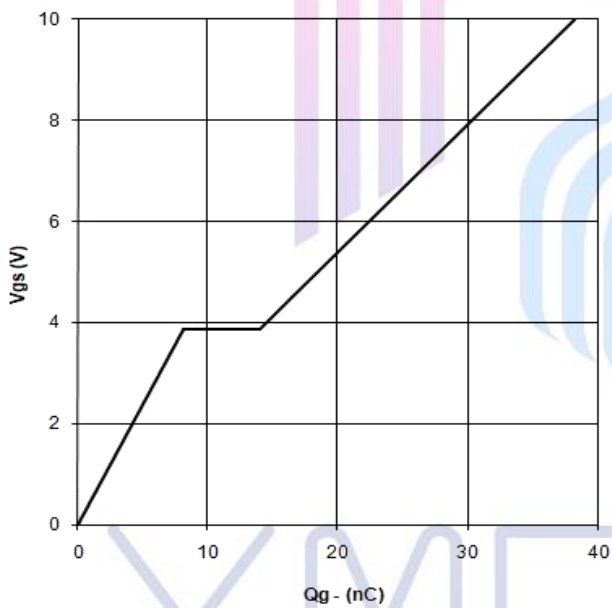
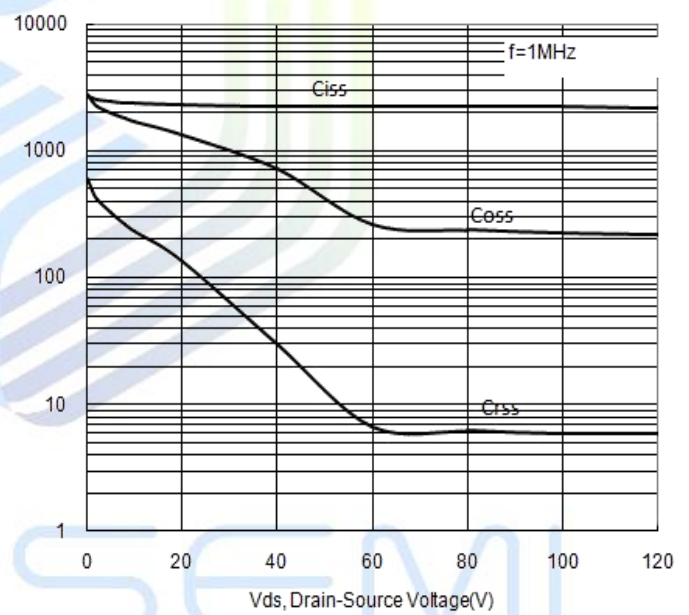
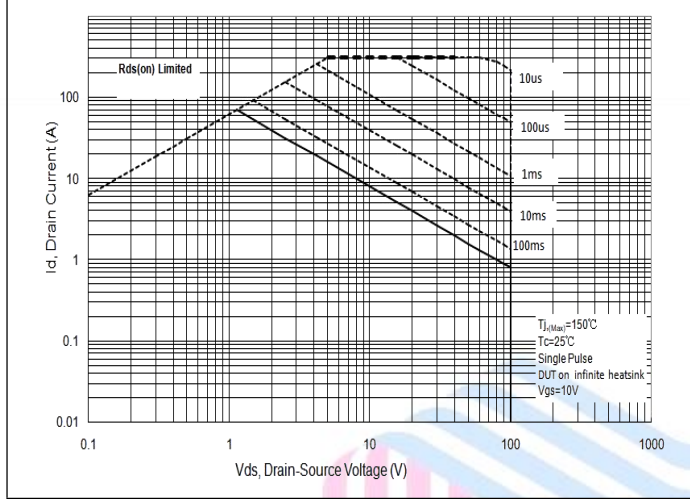
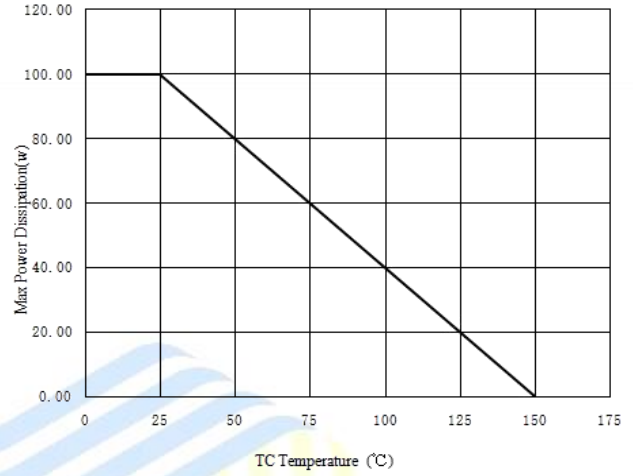
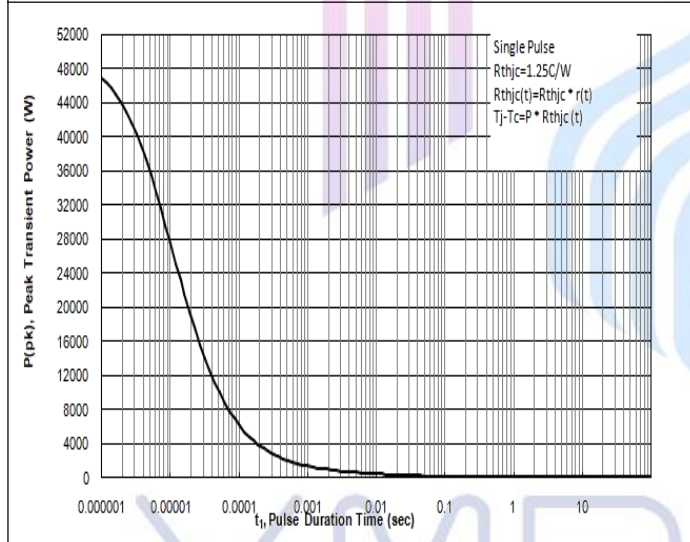
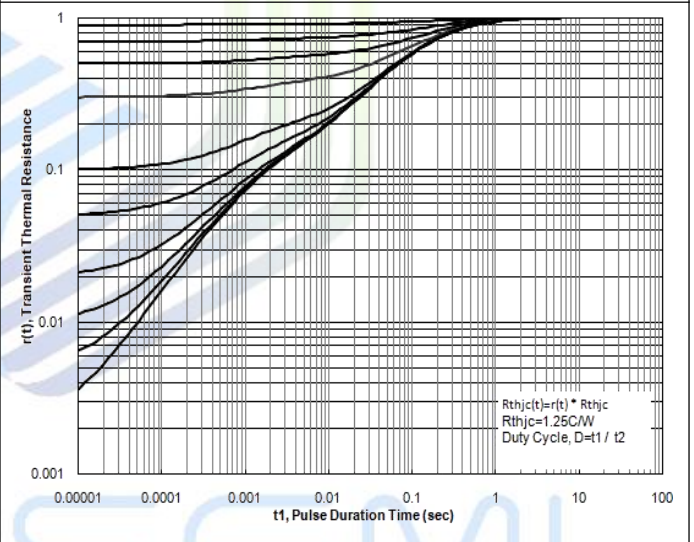
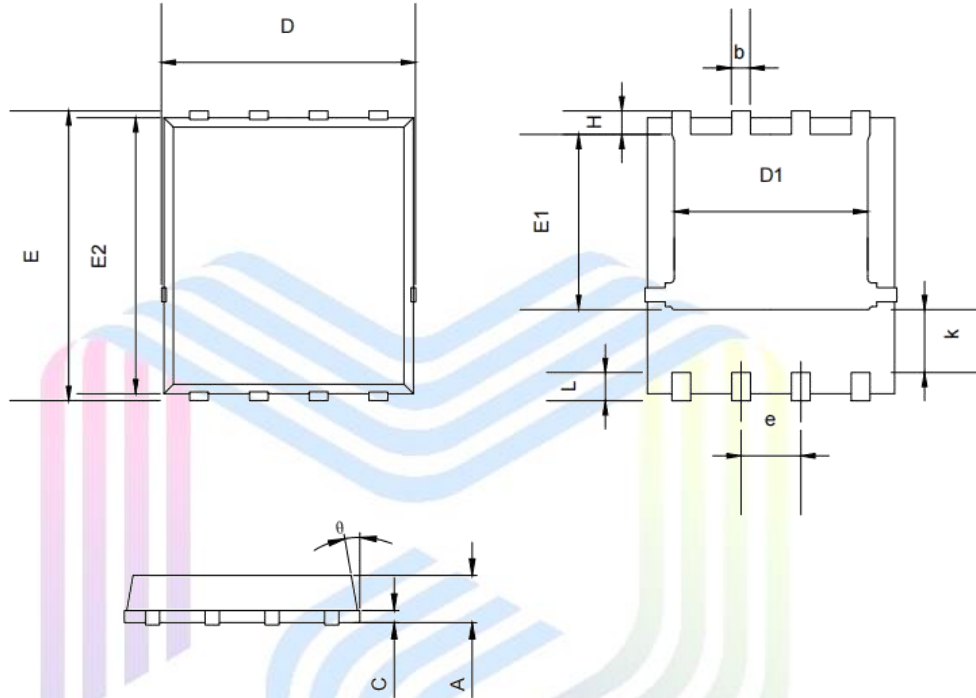
Figure 7: On-Resistance vs. Gate-source voltage

Figure 8: Forward Characteristics of Body Diode

Figure 9: Gate Charge Characteristics

Figure 10: Typ. Capacitances


Figure11: Safe Operating Area

Figure12: Power Dissipation

Figure 13: Single pulse power rating, Junction to case

Figure 14: Max transient thermal impedance


Mechanical Dimensions

PDFN5X6 Package Information



SYMBOL	MILLIMETERS	
	MIN	MAX
A	0.90	1.20
C	0.15	0.35
D	4.80	5.40
D1	3.61	4.31
E	5.90	6.35
E1	3.30	3.92
E2	5.50	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
H	0.38	0.71
θ	0°	12°

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